Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	38
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd20g18a-aut

1. Description

The Atmel® | SMART™ SAM D20 is a series of low-power microcontrollers using the 32-bit ARM® Cortex®-M0+ processor, and ranging from 32- to 64-pins with up to 256KB Flash and 32KB of SRAM. The SAM D20 devices operate at a maximum frequency of 48MHz and reach 2.46 CoreMark/MHz. They are designed for simple and intuitive migration with identical peripheral modules, hex compatible code, identical linear address map and pin compatible migration paths between all devices in the product series. All devices include intelligent and flexible peripherals, Atmel Event System for inter-peripheral signaling, and support for capacitive touch button, slider and wheel user interfaces.

The SAM D20 devices provide the following features: In-system programmable Flash, eight-channel Event System, programmable interrupt controller, up to 52 programmable I/O pins, 32-bit real-time clock and calendar, up to eight 16-bit Timer/Counters (TC) . The timer/counters can be configured to perform frequency and waveform generation, accurate program execution timing or input capture with time and frequency measurement of digital signals. The TCs can operate in 8- or 16-bit mode, selected TCs can be cascaded to form a 32-bit TC. The series provide up to six Serial Communication Modules (SERCOM) that each can be configured to act as an USART, UART, SPI, I^2C up to 400kHz, up to twenty-channel 350ksps 12-bit ADC with programmable gain and optional oversampling and decimation supporting up to 16-bit resolution, one 10-bit 350ksps DAC, two analog comparators with window mode, Peripheral Touch Controller supporting up to 256 buttons, sliders, wheels and proximity sensing; programmable Watchdog Timer, brown-out detector and power-on reset and two-pin Serial Wire Debug (SWD) program and debug interface.

All devices have accurate and low-power external and internal oscillators. All oscillators can be used as a source for the system clock. Different clock domains can be independently configured to run at different frequencies, enabling power saving by running each peripheral at its optimal clock frequency, and thus maintaining a high CPU frequency while reducing power consumption.

The SAM D20 devices have two software-selectable sleep modes, idle and standby. In idle mode the CPU is stopped while all other functions can be kept running. In standby all clocks and functions are stopped expect those selected to continue running. The device supports SleepWalking. This feature allows the peripheral to wake up from sleep based on predefined conditions, and thus allows the CPU to wake up only when needed, e.g. when a threshold is crossed or a result is ready. The Event System supports synchronous and asynchronous events, allowing peripherals to receive, react to and send events even in standby mode.

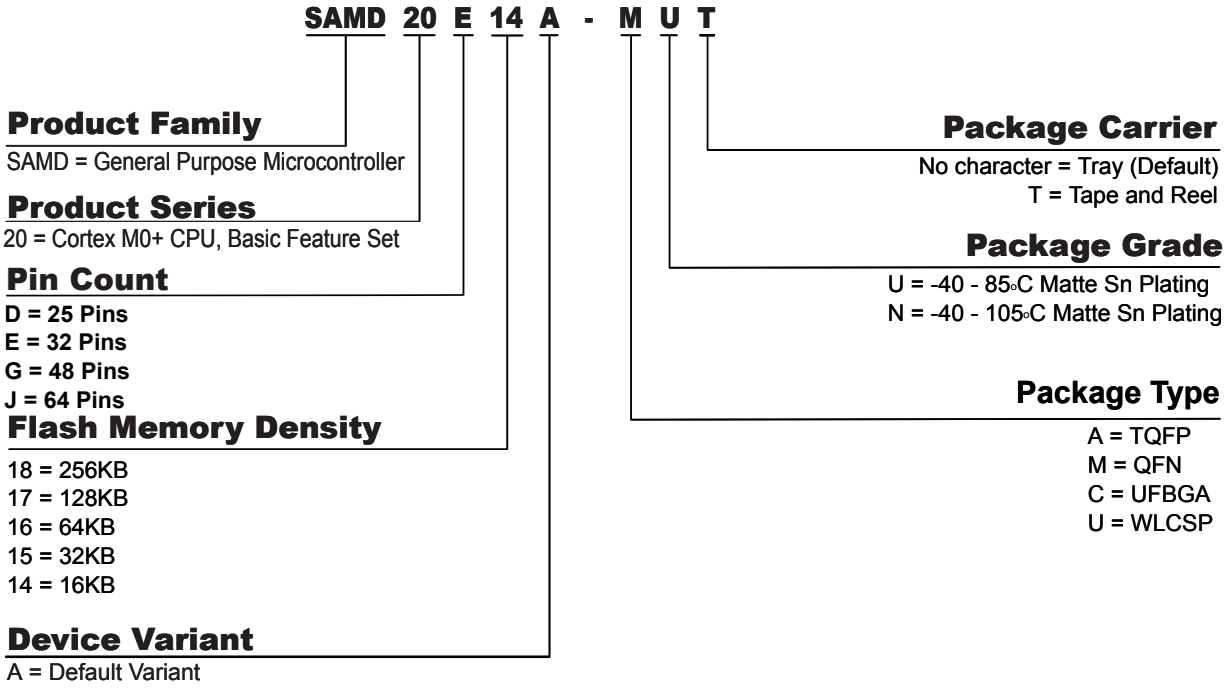
The Flash program memory can be reprogrammed in-system through the SWD interface. The same interface can be used for non-intrusive on-chip debug of application code. A boot loader running in the device can use any communication interface to download and upgrade the application program in the Flash memory.

The SAM D20 devices are supported with a full suite of program and system development tools, including C compilers, macro assemblers, program debugger/simulators, programmers and evaluation kits.

2. Configuration Summary

	SAM D20J	SAM D20G	SAM D20E
Pins	64	48	32
General Purpose I/O-pins (GPIOs)	52	38	26
Flash	256/128/64/32KB	256/128/64/32KB	256/128/64/32KB
SRAM	32/16/8/4/2KB	32/16/8/4/2KB	32/16/8/4/2KB
Timer Counter (TC) instances	8	6	6
Waveform output channels per TC instance	2	2	2
Serial Communication Interface (SERCOM) instances	6	6	4
Analog-to-Digital Converter (ADC) channels	20	14	10
Analog Comparators (AC)	2	2	2
Digital-to-Analog Converter (DAC) channels	1	1	1
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) X and Y lines	16x16	12x10	10x6
Maximum CPU frequency	48MHz		
Packages	QFN TQFP UFBGA	QFN TQFP WLCSP	QFN TQFP
Oscillators	32.768kHz crystal oscillator (XOSC32K) 0.4-32MHz crystal oscillator (XOSC) 32.768kHz internal oscillator (OSC32K) 32KHz ultra-low-power internal oscillator (OSCULP32K) 8MHz high-accuracy internal oscillator (OSC8M) 48MHz Digital Frequency Locked Loop (DFLL48M)		
Event System channels	8	8	8
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

3. Ordering Information



3.1. SAM D20E

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20E14A-AU	16K	2K	TQFP32	Tray
ATSAMD20E14A-AUT				Tape & Reel
ATSAMD20E14A-AN				Tray
ATSAMD20E14A-ANT				Tape & Reel
ATSAMD20E14A-MU			QFN32	Tray
ATSAMD20E14A-MUT				Tape & Reel
ATSAMD20E14A-MN				Tray
ATSAMD20E14A-MNT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20J18A-AU	256K	32K	TQFP64	Tray
ATSAMD20J18A-AUT				Tape & Reel
ATSAMD20J18A-AN				Tray
ATSAMD20J18A-ANT				Tape & Reel
ATSAMD20J18A-MU			QFN64	Tray
ATSAMD20J18A-MUT				Tape & Reel
ATSAMD20J18A-MN				Tray
ATSAMD20J18A-MNT				Tape & Reel
ATSAMD20J18A-CU			UFBGA64	Tray
ATSAMD20J18A-CUT				Tape & Reel

3.4. Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The device variants have a reset value of DID=0x1001drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').

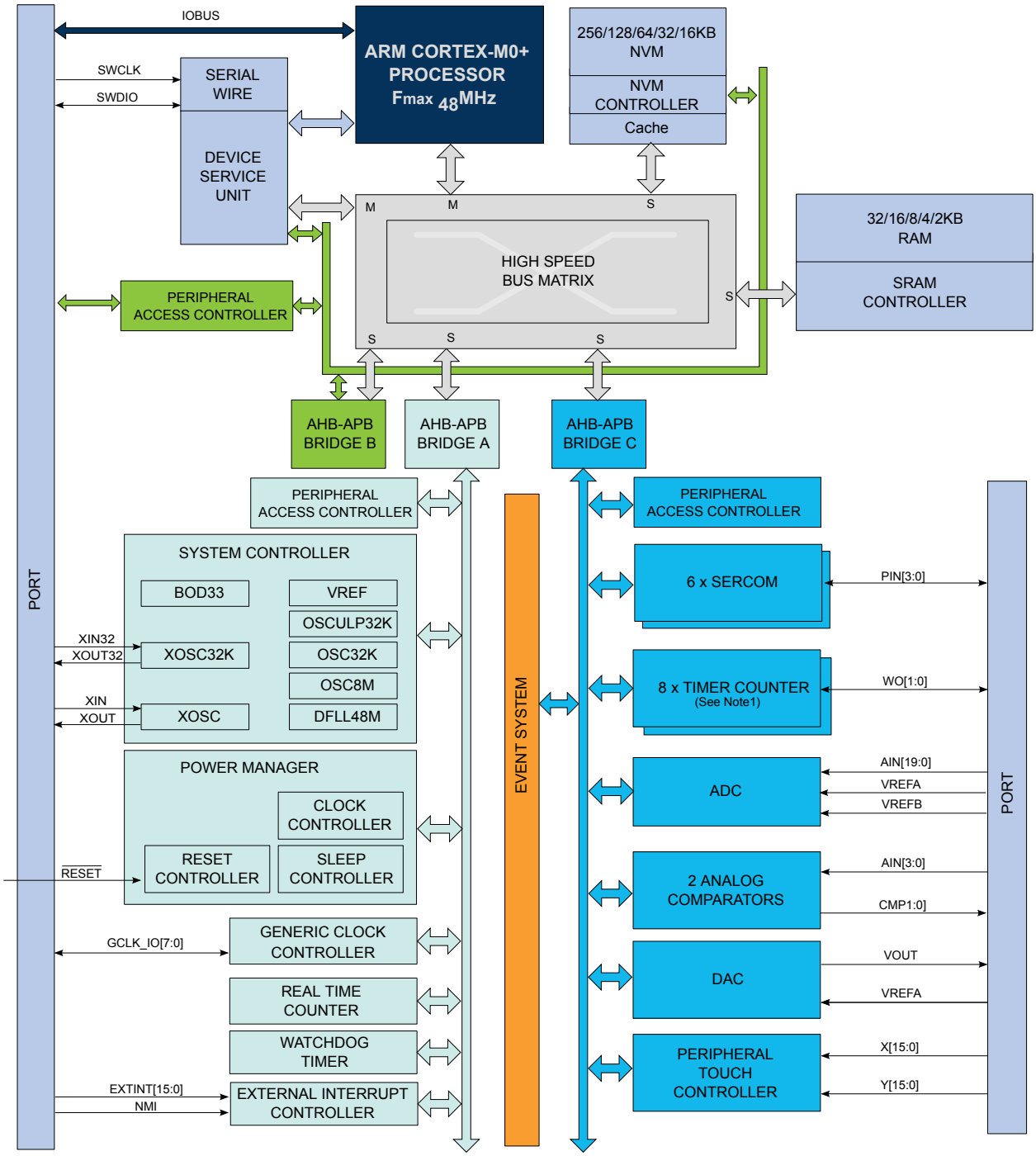
Table 3-1. Device Identification Values

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20J18C	0x00	0x10001300
SAMD20J18A	0x00	0x10001300
SAMD20J17A	0x01	0x10001301
SAMD20J16A	0x02	0x10001302
SAMD20J15A	0x03	0x10001303
SAMD20J14A	0x04	0x10001304
SAMD20G18A	0x05	0x10001305
SAMD20G17A	0x06	0x10001306
SAMD20G16A	0x07	0x10001307
SAMD20G15A	0x08	0x10001308
SAMD20G14A	0x09	0x10001309
SAMD20E18A	0x0A	0x1000130A
SAMD20E17A	0x0B	0x1000130B
SAMD20E16A	0x0C	0x1000130C
SAMD20E15A	0x0D	0x1000130D

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20E14A	0x0E	0x1000130E
Reserved	0x0F	
SAMD20G18U	0x10	0x10001310
SAMD20G17U	0x11	0x10001311
Reserved	0x12 - 0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

4. Block Diagram

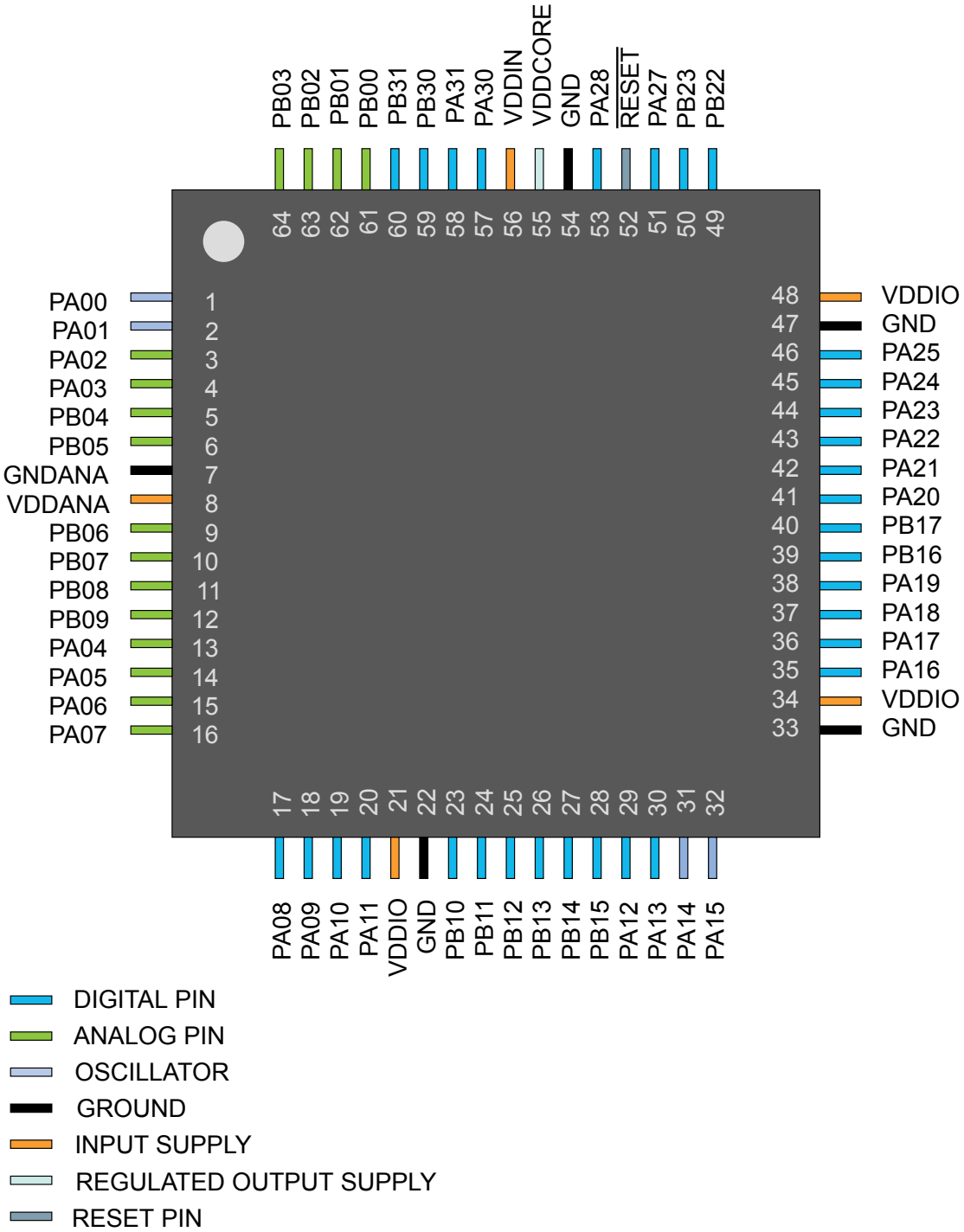


Note: 1. Some products have different number of SERCOM instances, Timer/Counter instances, PTC signals and ADC signals. Refer to *Peripherals Configuration Summary* for details.

5. Pinout

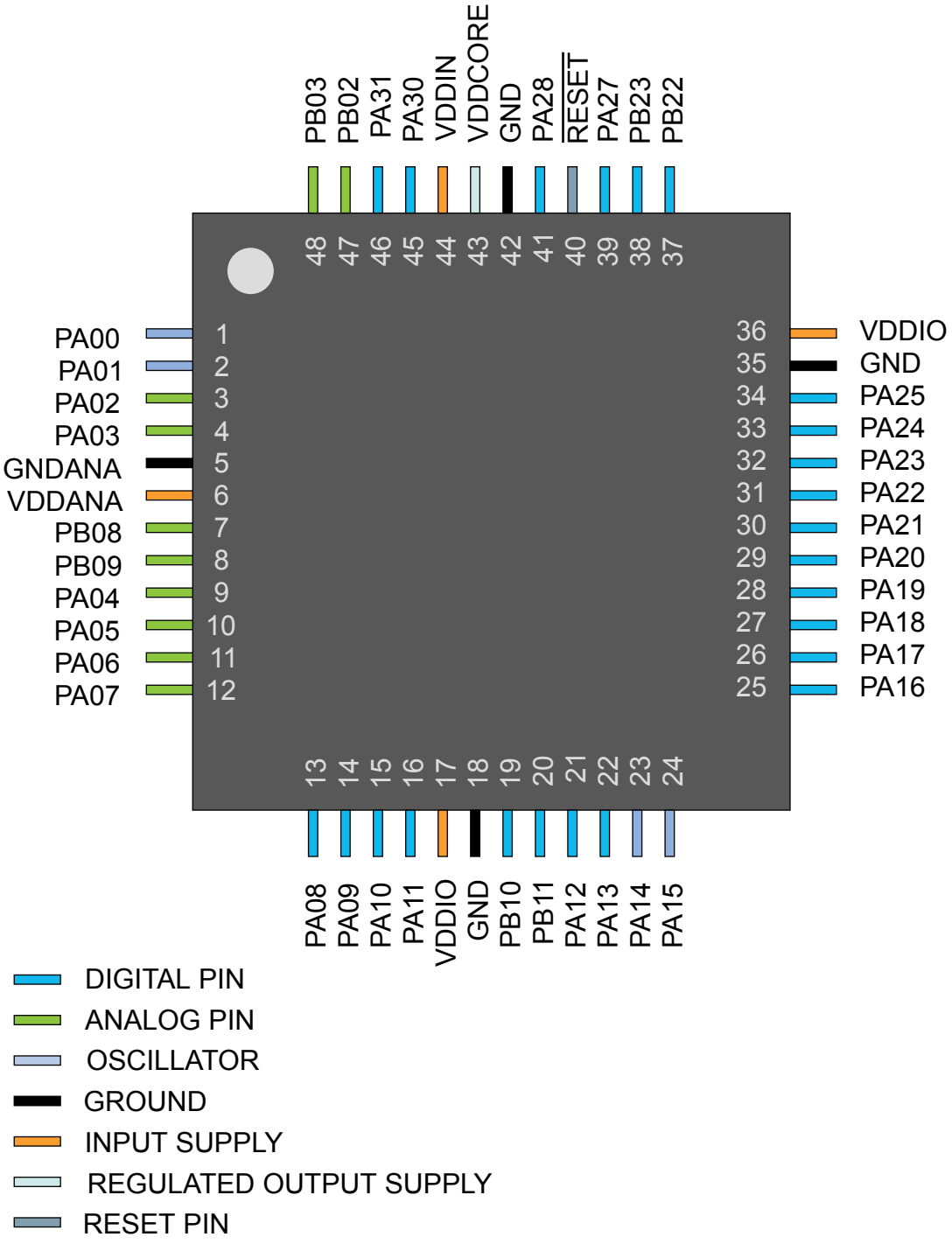
5.1. SAM D20J

5.1.1. QFN64 / TQFP64



5.2. SAM D20G

5.2.1. QFN48 / TQFP48



Peripheral Source	NVIC Line
DAC – Digital-to-Analog Converter	23
PTC – Peripheral Touch Controller	24

7.3. Micro Trace Buffer

7.3.1. Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2. Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

Figure 7-1. APB Write Access.

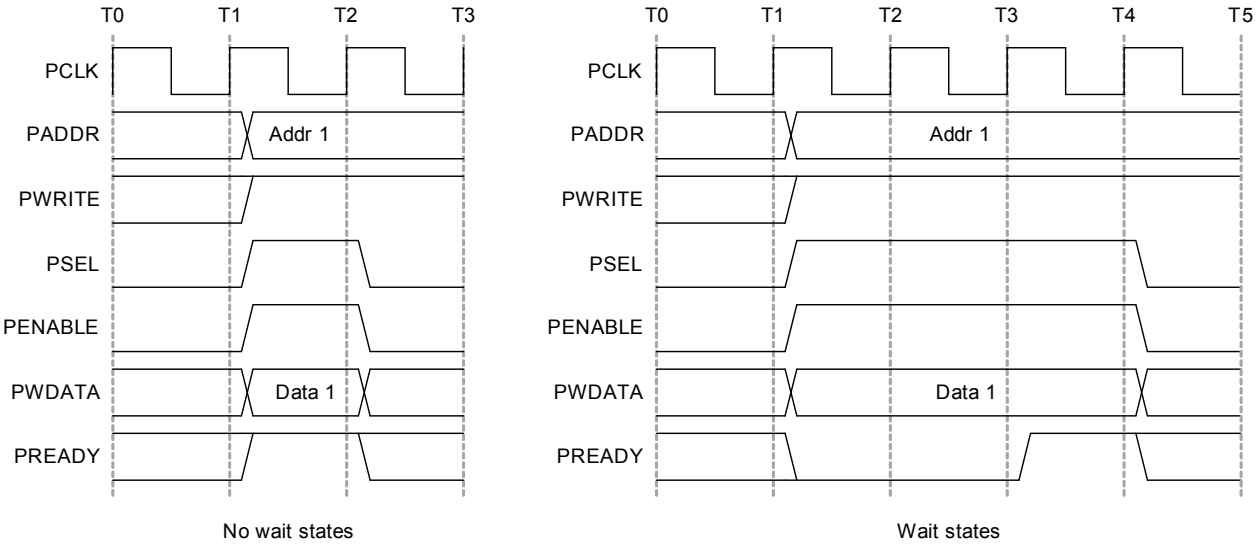
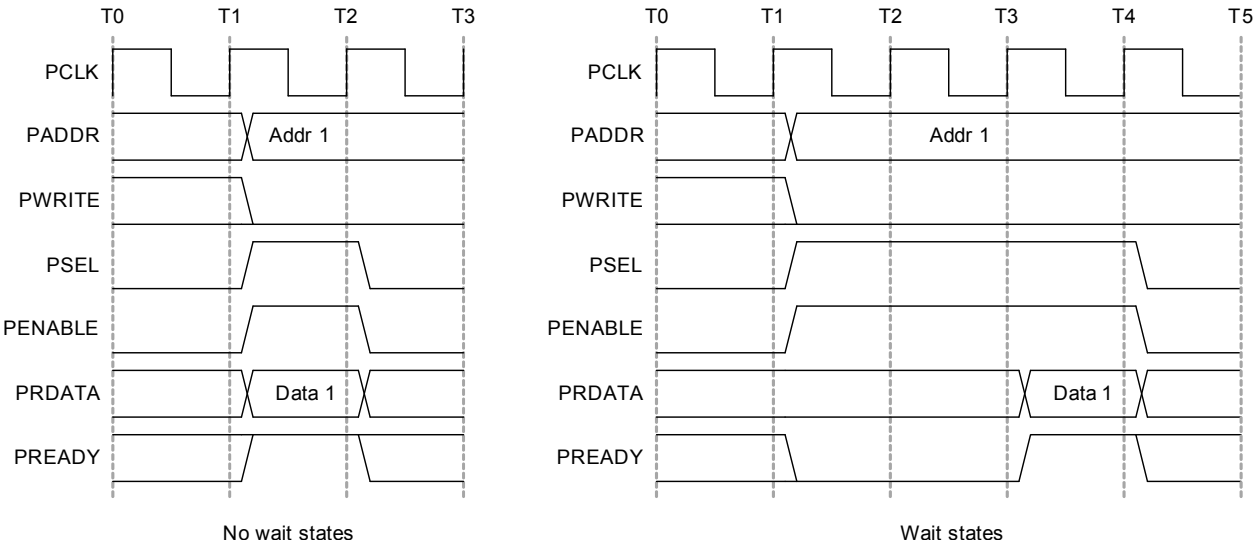


Figure 7-2. APB Read Access.



Related Links

Product Mapping on page 19

7.6. PAC - Peripheral Access Controller

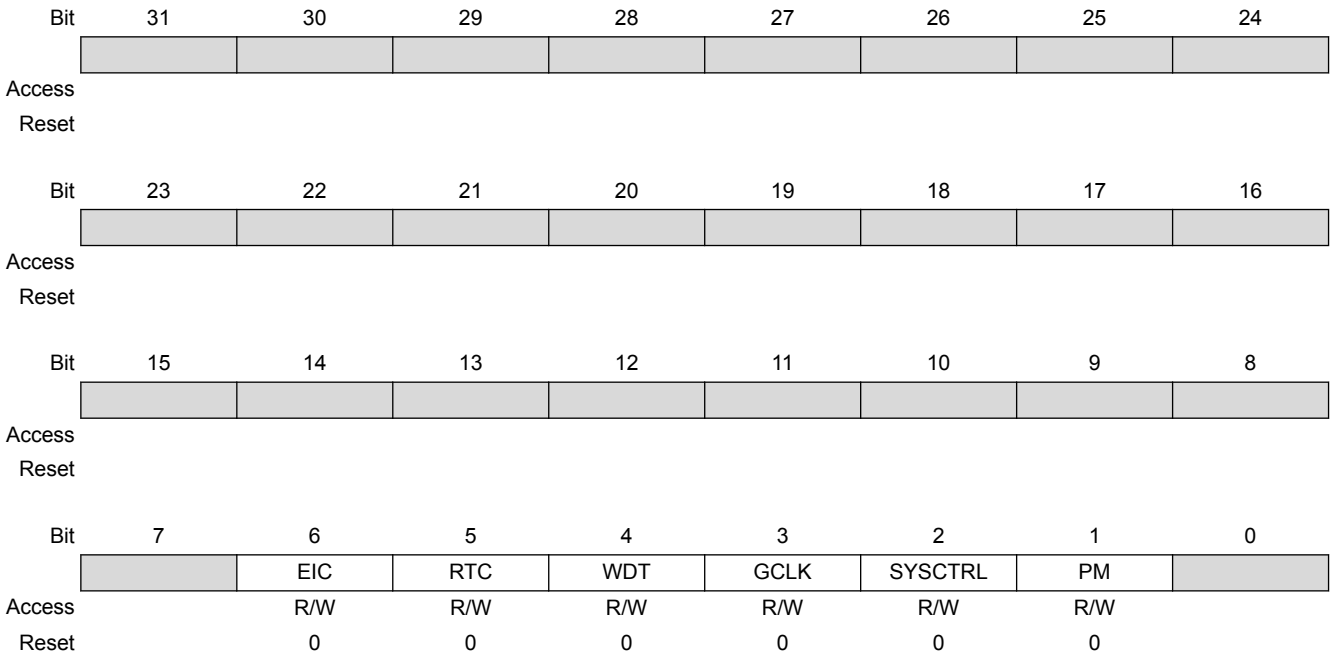
7.6.1. Overview

There is one PAC associated with each AHB-APB bridge. The PAC can provide write protection for registers of each peripheral connected on the same bridge.

The PAC peripheral bus clock (CLK_PACx_APB) can be enabled and disabled in the Power Manager. CLK_PAC0_APB and CLK_PAC1_APB are enabled are reset. CLK_PAC2_APB is disabled at reset. Refer to *PM – Power Manager* for details. The PAC will continue to operate in any sleep mode where the selected clock source is running. Write-protection does not apply for debugger access. When the debugger makes an access to a peripheral, write-protection is ignored so that the debugger can update the register.

7.7.1.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000000
Property: –



Bit 6 – EIC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – RTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

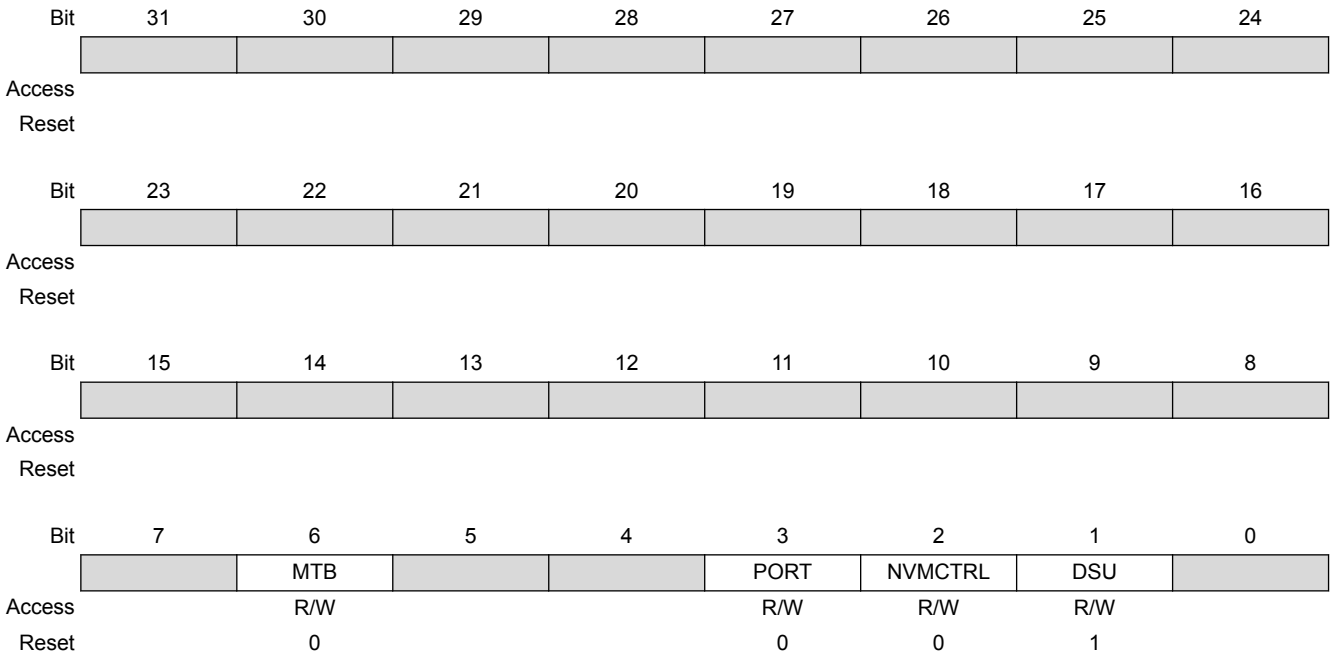
Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 4 – WDT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

7.7.2.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000002
Property: –



Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
Access								
Reset								

Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		MTB			PORT	NVMCTRL	DSU	
Access		R/W			R/W	R/W	R/W	
Reset		0			0	0	1	

Bit 6 – MTB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

7.7.3.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x00800000
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
					PTC	DAC	AC	ADC
Access					R/W	R/W	R/W	R/W
Reset					0	0	0	0

Bit	15	14	13	12	11	10	9	8
	TC7	TC6	TC5	TC4	TC3	TC2	TC1	TC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
	SERCOM5	SERCOM4	SERCOM3	SERCOM2	SERCOM1	SERCOM0	EVSYS	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	

Bit 19 – PTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 18 – DAC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 16 – ADC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 15,14,13,12,11,10,9,8 – TCx
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 7,6,5,4,3,2 – SERCOMx
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

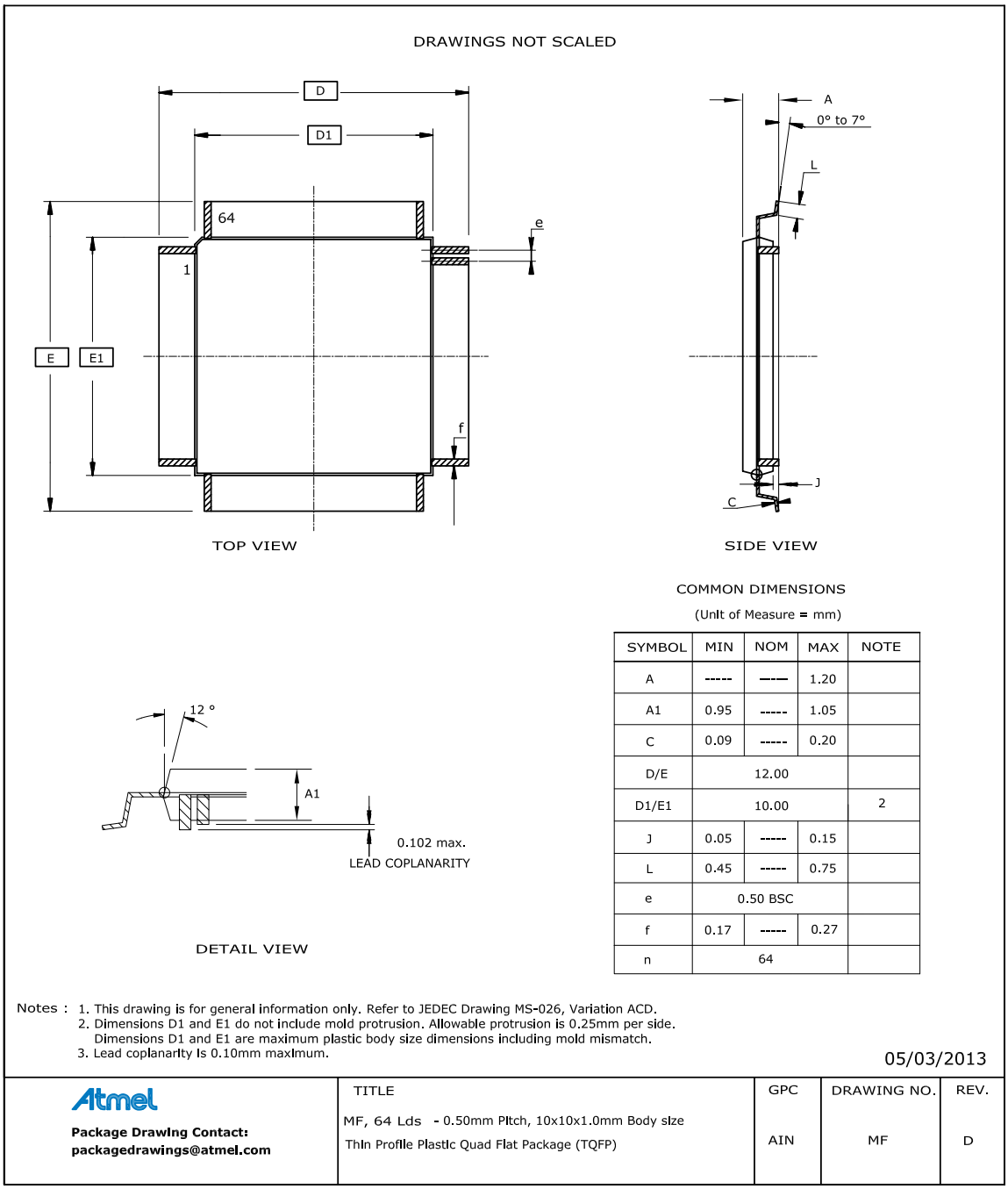
Bit 1 – EVSYS
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

8.2. Package Drawings

8.2.1. 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes :
1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

Atmel Package Drawing Contact: packagedrawings@atmel.com	TITLE MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	GPC AIN	DRAWING NO. MF	REV. D

Table 8-2. Device and Package Maximum Weight

300	mg

Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-5. Device and Package Maximum Weight

200	mg

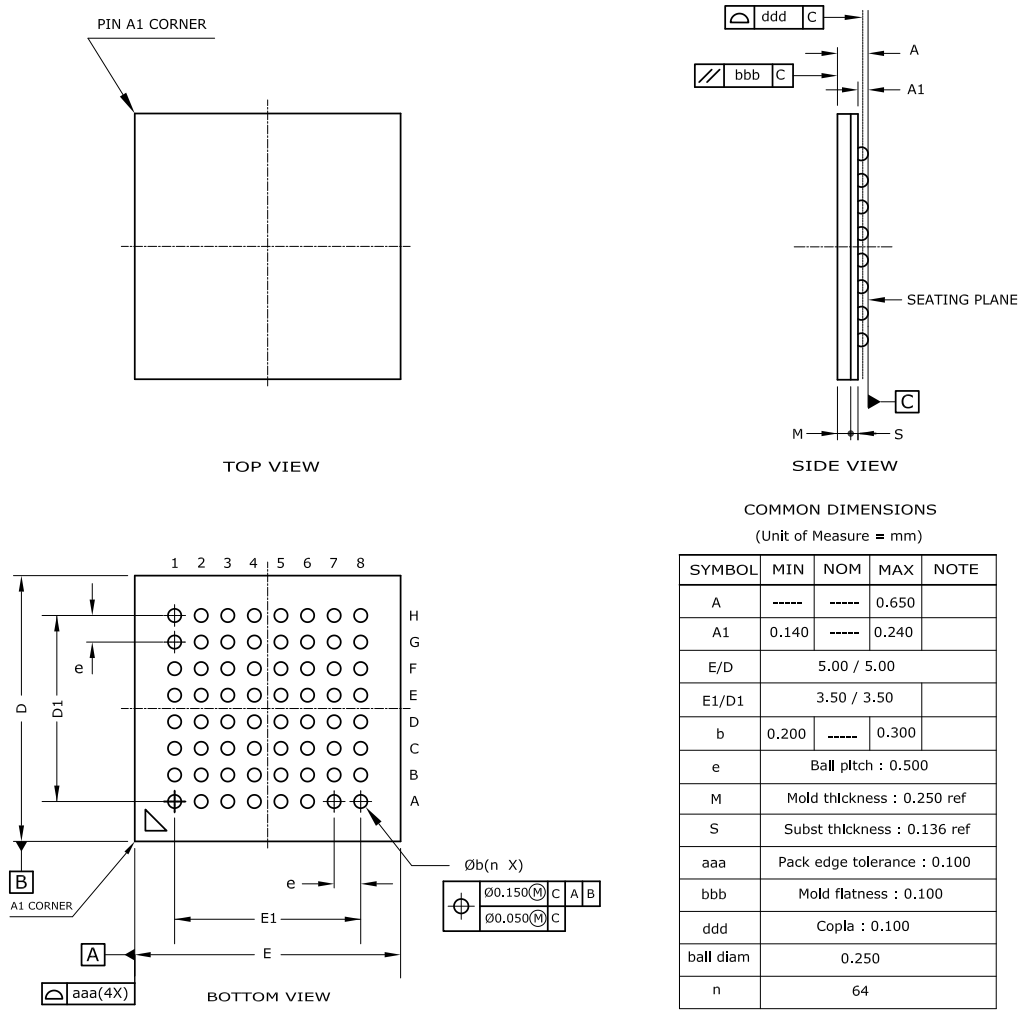
Table 8-6. Package Charateristics

Moisture Sensitivity Level	MSL3

Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.3. 64-ball UFBGA



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	0.650	
A1	0.140	-----	0.240	
E/D	5.00 / 5.00			
E1/D1	3.50 / 3.50			
b	0.200	-----	0.300	
e	Ball pitch : 0.500			
M	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla : 0.100			
ball diam	0.250			
n	64			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
2. Array as seen from the bottom of the package.
3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 8-8. Device and Package Maximum Weight

27.4	mg

Table 8-11. Device and Package Maximum Weight

140	mg

Table 8-12. Package Characteristics

Moisture Sensitivity Level	MSL3

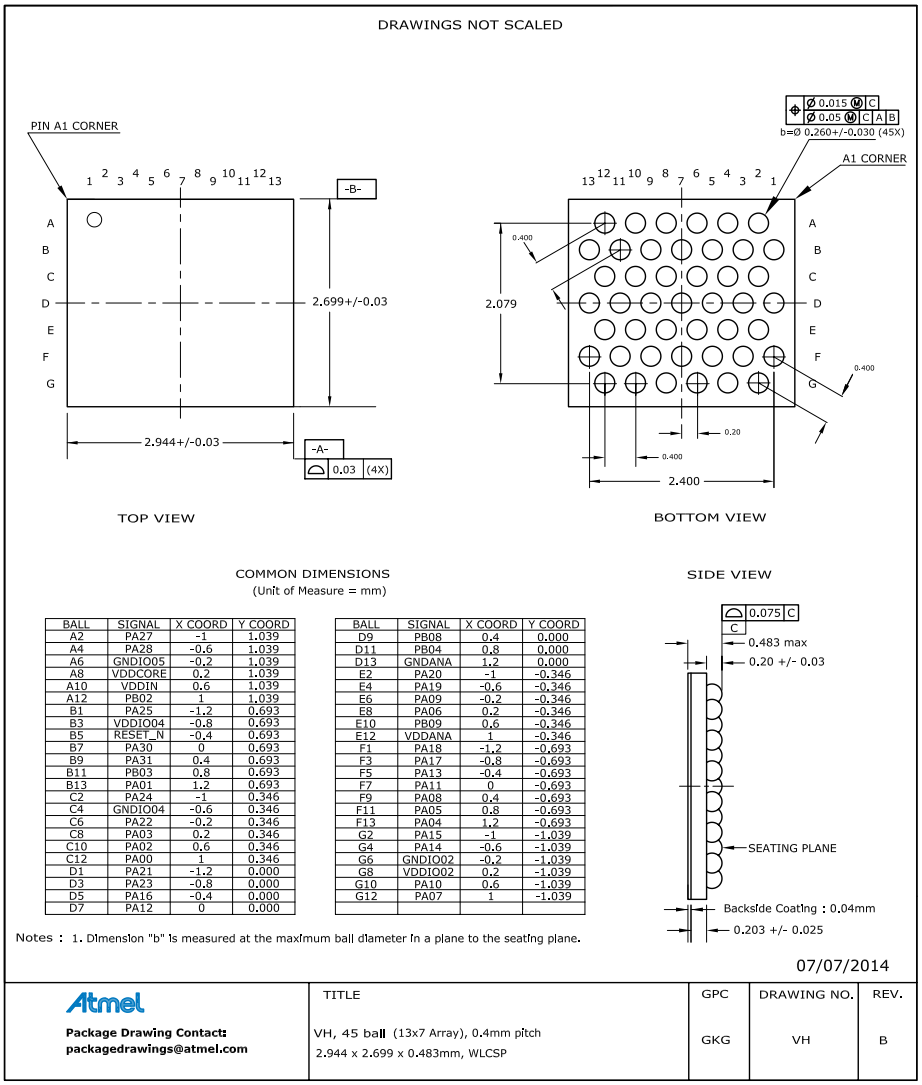
Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

Table 8-16. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.6. 45-ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A2	PA27	-1	1.039
A4	PA28	-0.6	1.039
A6	GNDIO05	-0.2	1.039
A8	VDDCORE	0.2	1.039
A10	VDDIN	0.6	1.039
A12	PB02	1	1.039
B1	PA25	-1.2	0.693
B3	VDDIO04	-0.8	0.693
B5	RESET_N	-0.4	0.693
B7	PA30	0	0.693
B9	PA31	0.4	0.693
B11	PB03	0.8	0.693
B13	PA01	1.2	0.693
C2	PA24	-1	0.346
C4	GNDIO04	-0.6	0.346
C6	PA22	-0.2	0.346
C8	PA03	0.2	0.346
C10	PA02	0.6	0.346
C12	PA00	1	0.346
D1	PA21	-1.2	0.000
D3	PA23	-0.8	0.000
D5	PA16	-0.4	0.000
D7	PA12	0	0.000

BALL	SIGNAL	X COORD	Y COORD
D9	PB08	0.4	0.000
D11	PB04	0.8	0.000
D13	GNDANA	1.2	0.000
E2	PA20	-1	-0.346
E4	PA19	-0.6	-0.346
E6	PA09	-0.2	-0.346
E8	PA06	0.2	-0.346
E10	PB09	0.6	-0.346
E12	VDDANA	1	-0.346
F1	PA18	-1.2	-0.693
F3	PA17	-0.8	-0.693
F5	PA13	-0.4	-0.693
F7	PA11	0	-0.693
F9	PA08	0.4	-0.693
F11	PA05	0.8	-0.693
F13	PA04	1.2	-0.693
G2	PA15	-1	-1.039
G4	PA14	-0.6	-1.039
G6	GNDIO02	-0.2	-1.039
G8	VDDIO02	0.2	-1.039
G10	PA10	0.6	-1.039
G12	PA07	1	-1.039

Table 8-17. Device and Package Maximum Weight

7.3	mg

Table 8-18. Package Characteristics

Moisture Sensitivity Level	MSL1

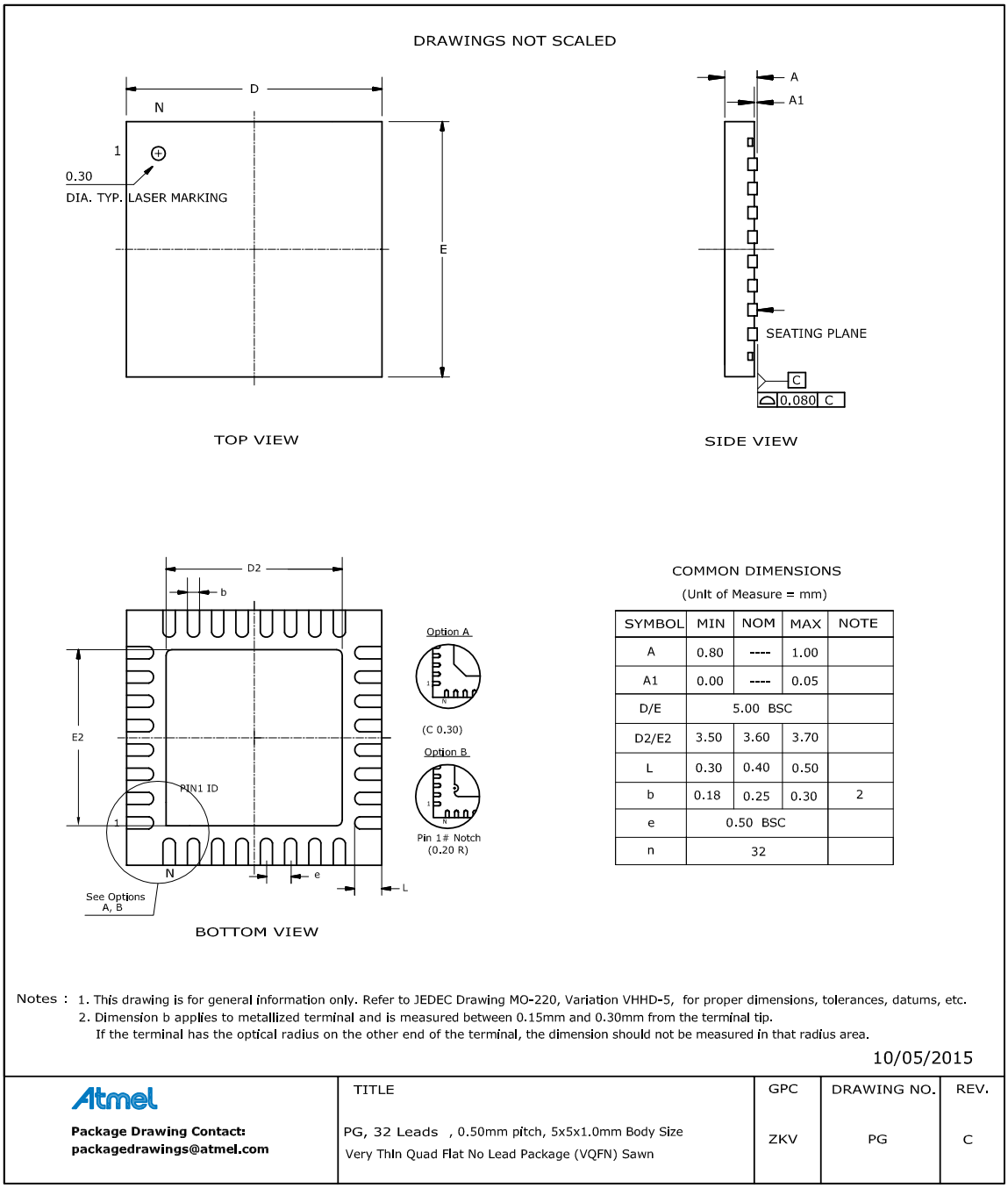
Table 8-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

Table 8-22. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.8. 32 pin QFN



Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-23. Device and Package Maximum Weight

90	mg

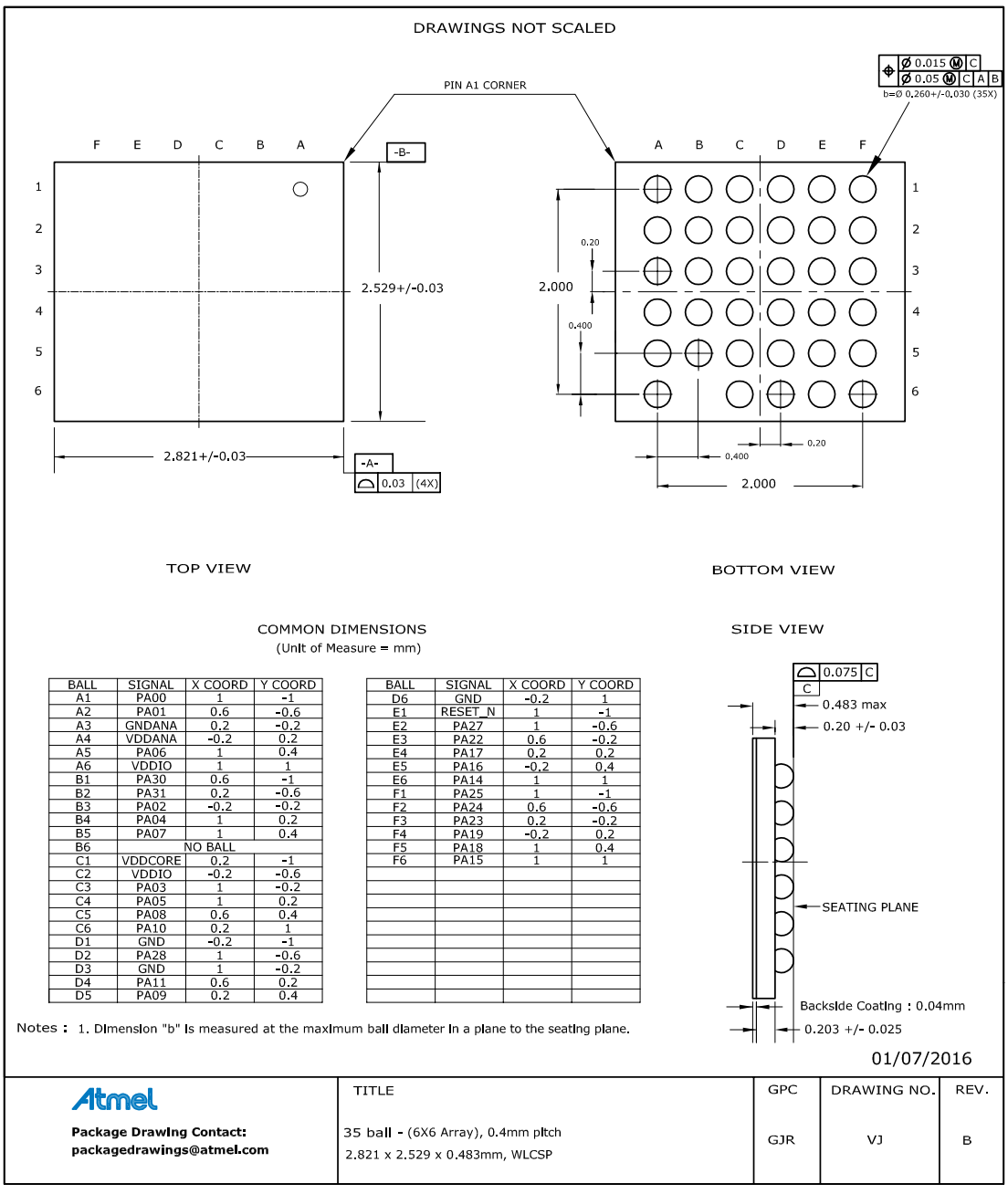
Table 8-24. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-25. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.9. 35 ball WLCSP



BALL	SIGNAL	X COORD	Y COORD
A1	PA00	1	-1
A2	PA01	0.6	-0.6
A3	GNDANA	0.2	-0.2
A4	VDDANA	-0.2	0.2
A5	PA06	1	0.4
A6	VDDIO	1	1
B1	PA30	0.6	-1
B2	PA31	0.2	-0.6
B3	PA02	-0.2	-0.2
B4	PA04	1	0.2
B5	PA07	1	0.4
B6	NO BALL		
C1	VDDCORE	0.2	-1
C2	VDDIO	-0.2	-0.6
C3	PA03	1	-0.2
C4	PA05	1	0.2
C5	PA08	0.6	0.4
C6	PA10	0.2	1
D1	GND	-0.2	-1
D2	PA28	1	-0.6
D3	GND	1	-0.2
D4	PA11	0.6	0.2
D5	PA09	0.2	0.4

BALL	SIGNAL	X COORD	Y COORD
D6	GND	-0.2	1
E1	RESET_N	1	-1
E2	PA27	1	-0.6
E3	PA22	0.6	-0.2
E4	PA17	0.2	0.2
E5	PA16	-0.2	0.4
E6	PA14	1	1
F1	PA25	1	-1
F2	PA24	0.6	-0.6
F3	PA23	0.2	-0.2
F4	PA19	-0.2	0.2
F5	PA18	1	0.4
F6	PA15	1	1

Table 8-26. Device and Package Maximum Weight

6.2	mg